

VAKSiS

R&D AND ENGINEERING

RIE-handy®



PRODUCT INFORMATION

Reactive-Ion Etching (RIE) is an etching technology. RIE system's vacuum chamber geometry is in cylindrical shape. It uses chemically reactive plasma to remove material deposited on wafers. High-energy ions from the plasma attack the wafer surface and react with it.

TECHNICAL SPECIFICATIONS

Ultimate Vacuum Pressure	$\approx 10^{-7}$ Torr
Substrate Size	4" - 8" diameter
Cooling	Substrate Holder
Loading	From the lift-open top plate or Load Lock
Control	Fully Automatic
Power Sources	RF power supply
Number of MFC's for different Gas Types	Max. 12
Gas Cabinet	Included and Integrated to System Software
Additional Gas Safety	Available Upon Request

SOFTWARE

System operation by user-friendly software. It is not only the automation and control software but also coating management software which allows the user design his/her specific coating experiments, examine the process parameters used in the past, and use the recipes/coatings developed in the past without hustle.

Human and machine safeties are prime importance in the operations performed by the software. A graphical user interface will allow the user to see the status of the system during operation.